

SMT power inductors

Size 12.95 x 9.40 x 5.08

Series/Type: B82476B1xxxM100

Date: June 2013



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Size 12.95 x 9.40 x 5.08mm

Rated inductance 1 ... 1000 µH

Construction

- Ferrite core
- Winding: enamel copper wire
- Winding soldered to terminals
- Rugged design with plastic terminal carrier

Features

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- Qualified to AEC-Q200
- RoHS-compatible

Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics
- Consumer electronics

Terminals

- Base material CuSn6P
- Layer structure Ni, Sn (lead-free)
- Electro-plated

Marking

Marking on component:
Manufacturer, L value (in µH), date code
Minimum data on reel:
Manufacturer, part number, ordering code,
L value and tolerance
quantity, date of packing

Delivery mode and packaging unit

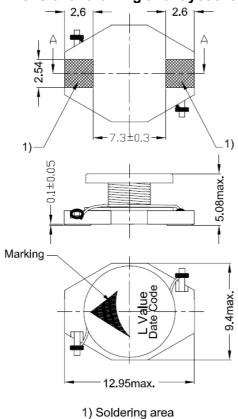
- 24-mm blister tape, reel packing
- Packaging quantity: 750 pcs./reel

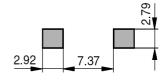




Size 12.95 x 9.40 x 5.08mm

Dimensional drawing and layout recommendation

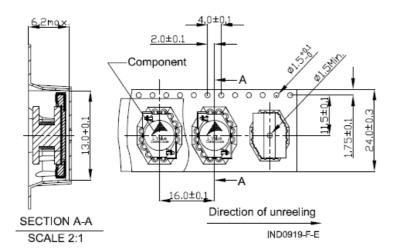




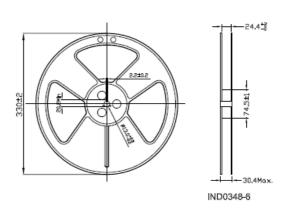
Dimensions in mm Component tolerances $\pm \text{0.2mm}$ unless otherwise noted

Taping and packing

Blister tape



Reel



Dimensions in mm

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Technical data and measuring conditions

ncy f _L , 0.1 V				
-55 °C +150 °C				
Max. permissible DC with temperature increase of ≤ 40 K at +20 °C				
Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%,				
Dip and look method Sn95.5Ag3.8Cu0.7:				
D)				
Mounted: -55 °C +150 °C				
/				

Characteristics and ordering codes

$\overline{L_R}$	Tolerance	f _L	I _R	I _{sat,min}	I _{sat,typ}	R _{max}	R _{typ}	Ordering code
μΗ		MHz	Α	Α	Α	Ω	Ω	
1.0	-		7.50	9.0	12.5	0.0080	0.0060	B82476B1102M100
1.5			6.90	8.0	10.0	0.0090	0.0070	B82476B1152M100
2.2			6.70	7.0	8.00	0.0105	0.0090	B82476B1222M100
3.3			5.90	6.4	6.80	0.0135	0.0115	B82476B1332M100
4.7			5.30	5.4	5.60	0.0165	0.0145	B82476B1472M100
6.8			4.80	4.6	4.90	0.0210	0.0190	B82476B1682M100
10			4.30	3.8	4.25	0.0270	0.0245	B82476B1103M100
15			3.40	3.0	3.40	0.0400	0.0350	B82476B1153M100
22			2.95	2.6	2.80	0.0500	0.0450	B82476B1223M100
33	20% = M	0.1	2.30	2.0	2.15	0.0880	0.0810	B82476B1333M100
47			1.95	1.6	2.05	0.120	0.110	B82476B1473M100
68			1.65	1.4	1.65	0.160	0.150	B82476B1683M100
100			1.40	1.2	1.35	0.230	0.215	B82476B1104M100
150			1.10	1.0	1.15	0.330	0.305	B82476B1154M100
220			0.88	0.8	0.88	0.530	0.480	B82476B1224M100
330			0.65	0.6	0.67	0.810	0.730	B82476B1334M100
470			0.55	0.5	0.56	1.100	1.010	B82476B1474M100
680			0.43	0.4	0.46	1.600	1.500	B82476B1684M100
1000			0.33	0.3	0.42	2.150	1.950	B82476B1105M100

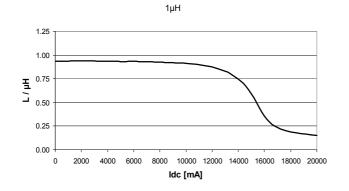
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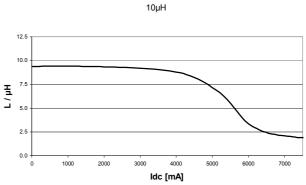


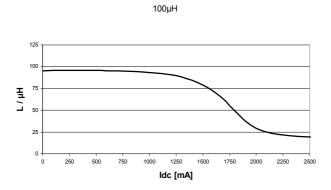
Size 12.95 x 9.40 x 5.08mm

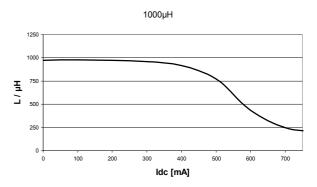
Typical curves:

Inductance vs. DC superposition measured with LCR meter Agilent 4284A at Ta=20 °C

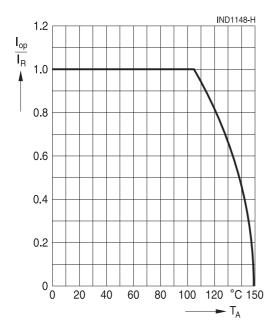








Current derating versus ambient temperature



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Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequecy behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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Partner in Electronic Components & Supply Chain Solutions



The Netherlands

Elektrostraat 17

NL-7483 PG Haaksbergen Tel: +31 (0)53 573 33 33 Fax: +31 (0)53 573 33 30 nl@texim-europe.com



Belgium

Gentsesteenweg 1154-C22 Chaussée de Gand 1154-C22 B-1082 Brussel / Bruxelles Tel: +32 (0)2 462 01 00 Fax: +32 (0)2 462 01 25

Fax: +32 (0)2 462 01 25 belgium@texim-europe.com



Germany

Justus-von-Liebig-Ring 7-9 D-25451 Quickborn

Tel: +49 (0)4106 627 07-0 Fax: +49 (0)4106 627 07-20 germany@texim-europe.com



Austria

Warwitzstrasse 9 A-5020 Salzburg

Tel: +43 (0)662 216026 Fax: +43 (0)662 216026-66 austria@texim-europe.com



Denmark

Nørregade 15 DK-9240 Nibe

Tel: +45 88 20 26 30 Fax: +45 88 20 26 39 nordic@texim-europe.com

United Kingdom

St. Mary's House, Church Lane Carlton Le Moorland Lincoln LN5 9HS

Tel: +44 (0)1522 789 555 Fax: +44 (0)845 299 22 26 uk@texim-europe.com



Germany

Martin-Kollar-Strasse 9 D-81829 München

Tel: +49 (0)89 436 086-0 Fax: +49 (0)89 436 086-19 germany@texim-europe.com

Texim Europe B.V.

Elektrostraat 17 NL-7483 PG Haaksbergen Tel: +31 (0)53 573 33 33 info@texim-europe.com

www.texim-europe.com

